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These statements may be identified by the use of forward-looking expressions, including, but not limited to, "expect," "anticipate," "believe," "estimate," "potential," "predict," "project," "should," "would," and similar expressions and the negatives of those terms. These statements relate to future events or our financial performance and involve known and unknown risks, uncertainties, and other factors which may cause actual results, performance or achievements to be materially different from any future results, performance or achievements expressed or implied by the forward-looking statements. Such factors include those set forth in the Company's filings with the Securities and Exchange Commission. Prospective investors are cautioned not to place undue reliance on such forward-looking statements, which speak only as of the date of this presentation. The Company undertakes no obligation to publicly update any forward-looking statement, whether as a result of new information, future events or otherwise.



OUTLINE OF SPEECH

Company Profile

- Our focus on the display market

What we are offering to the market

- The details

Date: 28 April, 2022

From: Steven Tsai

SmartKem Summary

Reshaping the World of Electronics

Market Leading Disruptive Technology

Recognized as the world-leading electronic material for organic transistors

- Headquartered in Manchester, UK (8,000ft2 R&D facility)
 - Foundry service for prototyping at UK's Centre for Process Innovation (CPI)
- Went public in March 2021 raising \$24.6m
- TRUFLEX® is a full transistor stack design and process platform
 - Owns Chemistry, Process and Stack design rules, proven to produce logic circuits at only 80°C with performance significantly beyond amorphous Silicon (a-Si)
 - Validated SPICE model and Process Design Kit (PDK)
- Flexible and can be produced on low cost plastic and glass
- Compatible with existing manufacturing lines or the printing processes that the industry plans to replace them
- Private and institutional investors including, AIGH, Octopus Ventures, Entrepreneurs Fund LP, BASF Ventures.

World Class Technology Team

- 42 (11 PhDs) FTEs with 200+ combined years industrial and R&D pedigree at ICI, Merck, Philips, Kodak, CDT, Motorola, Global Foundries
- Having developed the chemistry, the process, and the design rules, SmartKem is a fab-less company and has outsourced its chemistry scale-up.

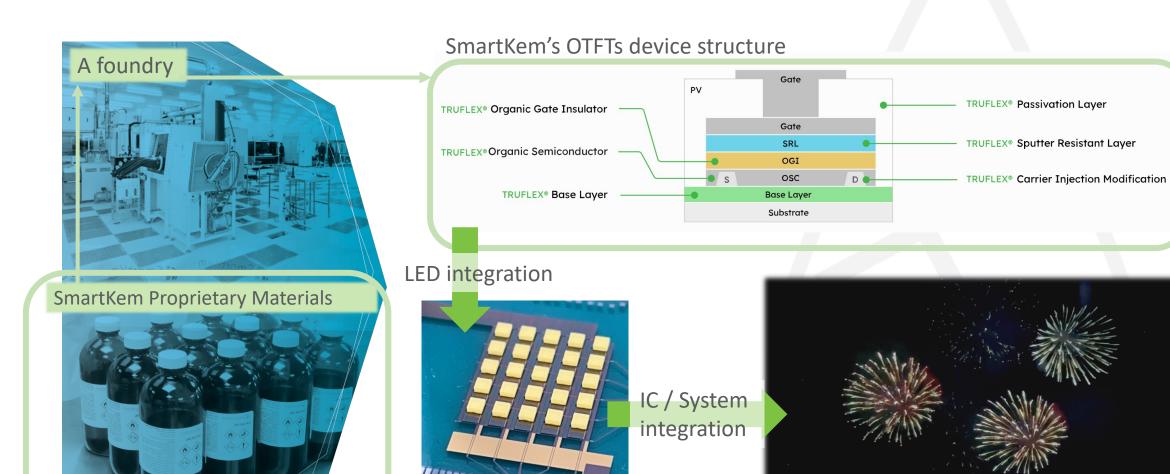
Extensive, Broad and Defendable IP Portfolio

- >133 patents across 16 patent families 122 granted and >16 pending
- >37 codified trade secrets

SmartKem Has Traction

- Traction at multiple technology companies producing OTFT based circuits including Mini-LED Backlights & sensors
- Launched first demonstrator at SID 2020

ORGANIC TRANSISTORS - THE FLOW



MARKET SIZE: MICRO-LED AS ULTIMATE TARGET



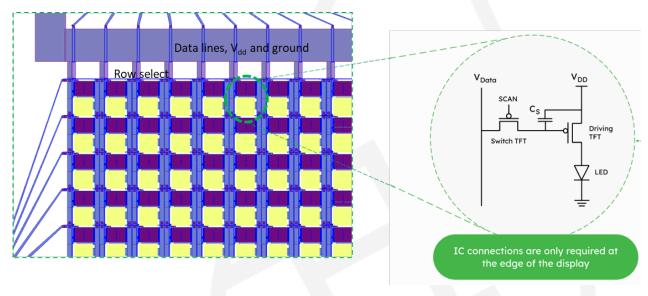
PASSIVE MATRIX (被動式) VS. ACTIVE MATRIX (主動式

Direct wiring



PCB based - 1152 LEDs (each of the 24 ICs is wired to 48 LEDs) - for several 000's of zones this becomes too costly

SmartKem Backplane active matrix driving scheme

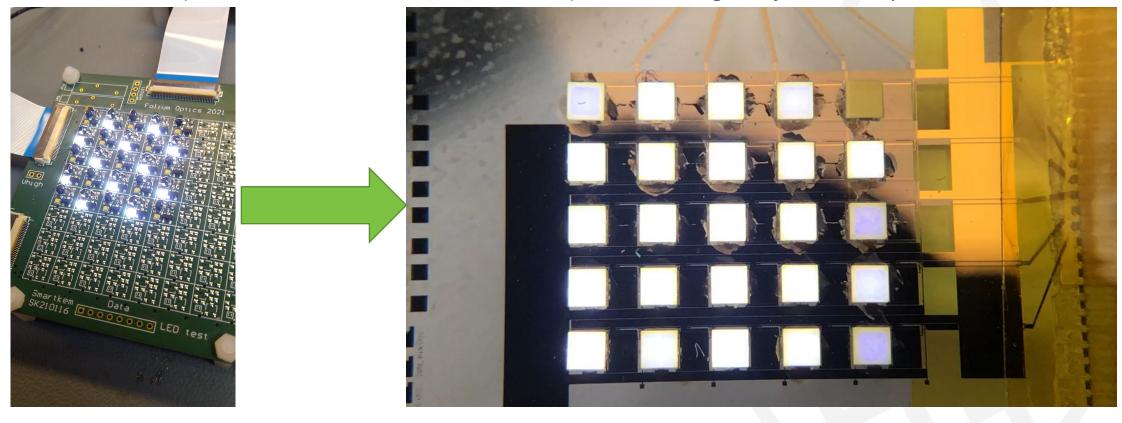


IC connections are only required at the edge of the display

- Low T Process flatter and less prone to substrate distortion
- Heat from LEDs can be conducted away from back of the substrate (no ICs in the way). On very thin plastic substrates so the thermal conduction is very efficient
- Backplane approach can be modified to microLED in future

A TRANSITION FROM CONVENTIONAL PCB TECHNOLOGY

All from SmartKem (此系列展示皆為SmartKem自主展品&技術) – From SmartLight Project funded by Innovate UK

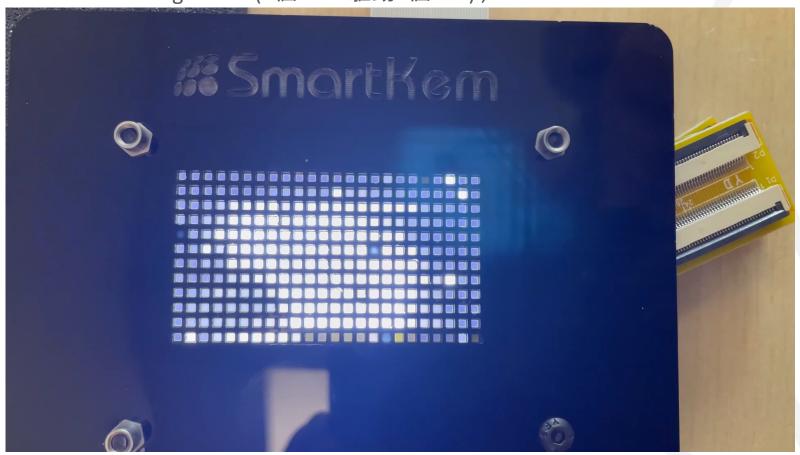


5x5 Si-MOSFET + surface mount capacitor circuit generated on a PCB for driver electronics evaluation

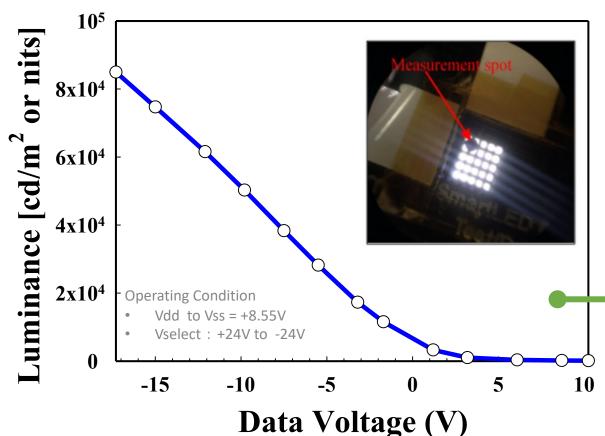
Upgrade to Active Matrix driving (driven by SmartKem OTFTs)

OTFTS-MINILED BLU DEMONSTRATOR: OTFTS PER LED

• 1 OTFTs driving 1 LED (1個OTFT驅動1個LED), 12x24 in total



BACKLIGHT LUMINANCE PERFORMANCE



Panel Brightness

- 85,000 nit brightness was measured
- Contrast ratio if 1,000,000 : 1

Working temperature

• LED temp ~30°C While Panel is working

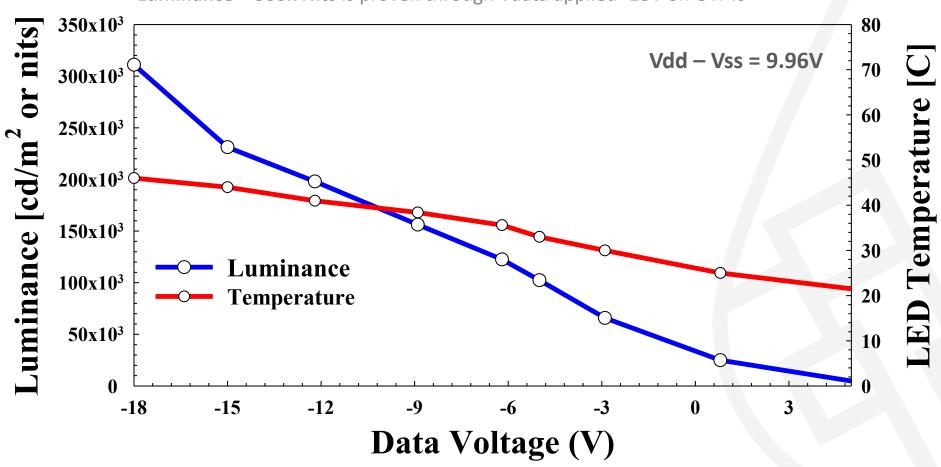
LCD integration as backlight component

- Equates to 4,250 nits front of the screen with a 5% LCD %T
- LCD native contrast ratio of 2000: 1)



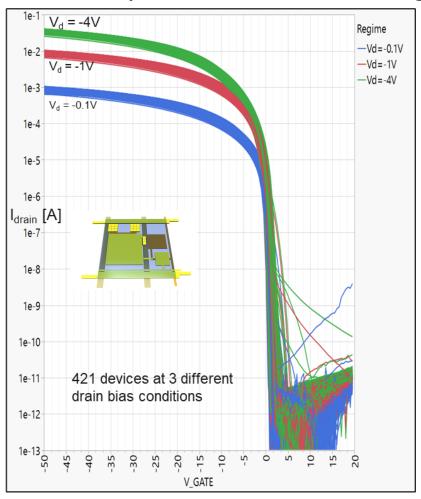
BACKLIGHT LUMINANCE PERFORMANCE

Luminance > 300k Nits is proven through Vdata applied -18V on OTFTs



DEMONSTRATORS: MINILED BACKLIGHTS

OTFTs device performance for Mini-LED Backlight demonstrators



- Median on current at Vd = -4V Vg = -50V is 40mA
- Off current is a few pA
- On/off ratio is ~10¹⁰

According to different LED current requirements, SmartKem has the ability to **optimize the TFT design**

$$I_{D} = \frac{W}{L} \mu C_{ox} (V_{g} - V_{th}) V_{d}$$

OUR CAPABILITY



- Substrate from 4inch to Gen2.5 (370*470mm2)
- Capability for a wide region of plastic substrates
- Full device testing & study could proceed in UK/Taiwan
- We could provide a "SmartKem laboratory" service to make your idea realized through lab-scale, implementing our proprietary materials (inks) to scale up through your preferred supply chain!

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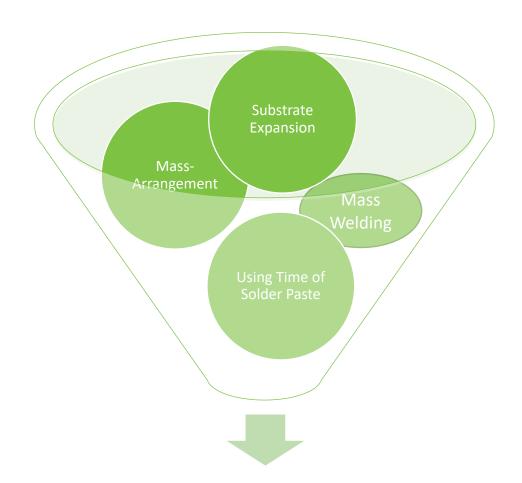
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KEY POINT FOR U-LED MASS TRANSFER



- Substrate Expansion (基板脹縮)
- Mass-Arrangement (巨量排列)
- Using Time of Solder Paste (錫膏使用時間)
- Mass Welding (巨量焊接)

SUBSTRATE EXPANSION

There are three different types of plastic substrates (commercialized):

	Item	NPG200R	IT-140GTC	EM825
	Taiwanese Supplier	Company N	Company I	Company E
	Туре	BT resin	No Halogen	-
	Tg (Degree C)	205 (DMA)	155 (DESC)	150 (DSC)
CTE (ppm / degree C)	CTE (Z axis before Tg)	35 ~45	35	50
	CTE (Z axis After Tg)	180~210	180~210	260
	CTE (X,Y Axis)	1.2~1.6	1.2~1.6	1.2~1.5
	Flammability (UL-94)	V0	V0	V0
	Peel strength (lbf/in) 剝離強度	6~9	8	6.5

SUBSTRATE EXPANSION FOR 16INCH PANEL

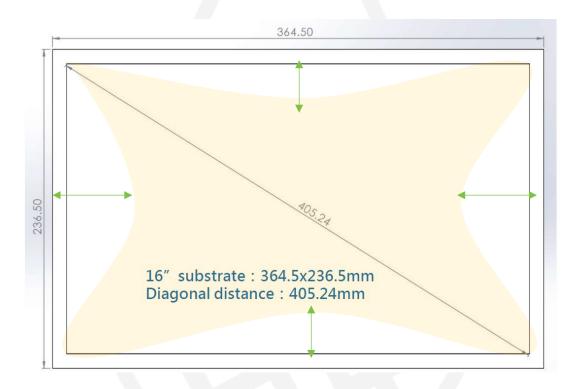
• Normal Soldering process ~ 240 °C (無鉛噴錫表面處理製程,約240 °C)

When CTE(ppm/°C) : **1.2~1.6** for X,Y direction 405.24mm x (**1.2**/ 10^6) x (**240** °C -25 °C) = 104.552um

• By OTFTs process + Low-temperature mounting (低溫背板製程)

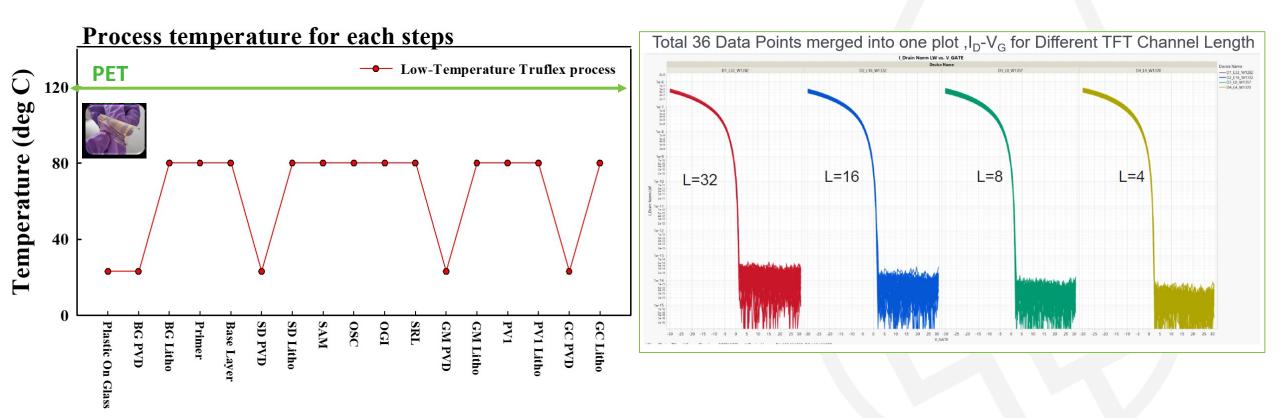
When CTE(ppm/°C) : **1.2~1.6** for X,Y direction 405.24mm x (**1.2**/ 10^6) x (80 °C -25 °C) = 26.746 um





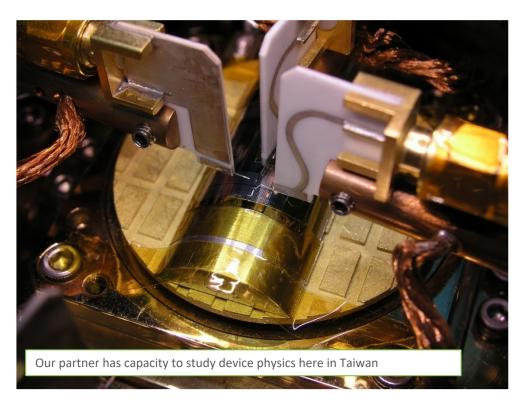
80 DEGREE-C OTFTS PROCESS

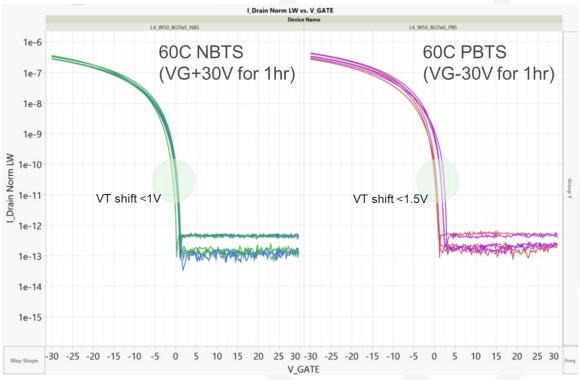
80 °C OTFTs process demonstrated consistent performance shown in ID-VG (36 data points merged)



80 DEGREE-C OTFTS PROCESS — ELECTRICAL STABILITY

- 1) 80 °C OTFTs process demonstrated excellent electrical stability (under high-temperature DC bias stress)
- 2) OTFTs device stability measured through fixed curve mechanical stress as separate studies

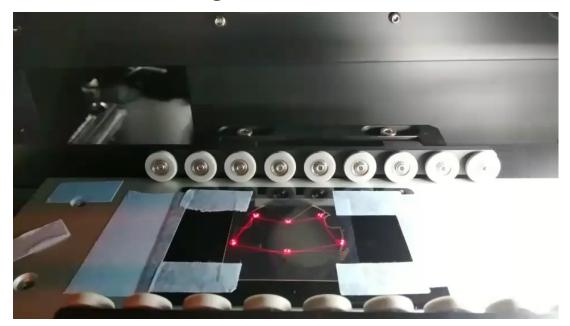




LOW TEMPERATURE MINI-LED MOUNTING ON **PET** SUBSTRATE

Background: eye tracking applications (especially near eyes display) requires an IR LED on a plastic substrate driven by TFT or IC.

Video – Laser mounting IR LED on PET substrate



Video – After LED mounting, Light-on test



^{*}Supported by our industrial partner, video Authorized to announce

ESG - ENVIRONMENT SOCIAL GOVERNANCE

Low-temperature backplane manufacturing is offering identical benefits for ESG production.

Material / Process		Unit	General	Recycled	Bio PET
Chip process	PTA	kg CO ₂ e/ton	1744	(A.T.):	1744
	EG	kg CO ₂ e/ton	480	72	0
	PTA+EG→PET Chip	kg CO ₂ e/ton	587	312	587
	Ratio of Reduction	%	-	88.90	17.08
Film process	PET Chip→PET Film	kg CO ₂ e/ton	3664	3664	3664
	Total	kg CO ₂ e/ton	6475	3977	5996
Total	Ratio of Reduction	%	-,	38.58	7.40

^{*}Data from public company



In PET substrate, a recycle PET is possible to Reduce >88% CO₂ emission

ESG - CONTINUOUS EFFORT FROM SMARTKEM

SmartKem's efforts go beyond that of organic electronics. We are continuously striving to help the planet by planting trees. SmartKem will donate over **11,500** trees in 2022!

Kenya (肯亞)







Peru – Quellccanca





Malawi (馬拉威)







Warwickshire, England, UK





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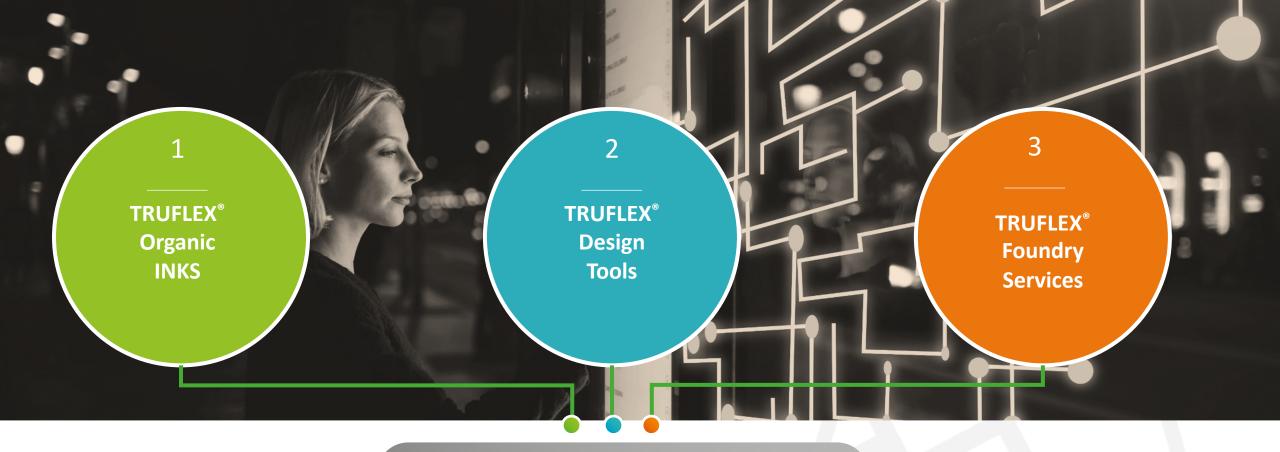
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Mass Deployment

SmartKem welcomes collaboration in the development of min-/u-LED applications!



THANK YOU

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